

# MECHANICAL CASE OUTLINE

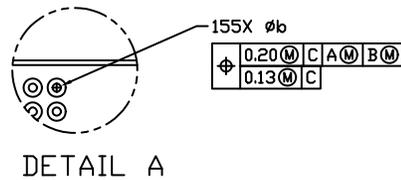
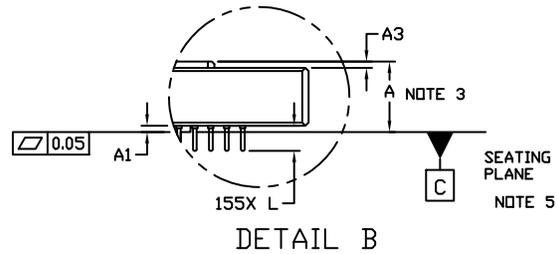
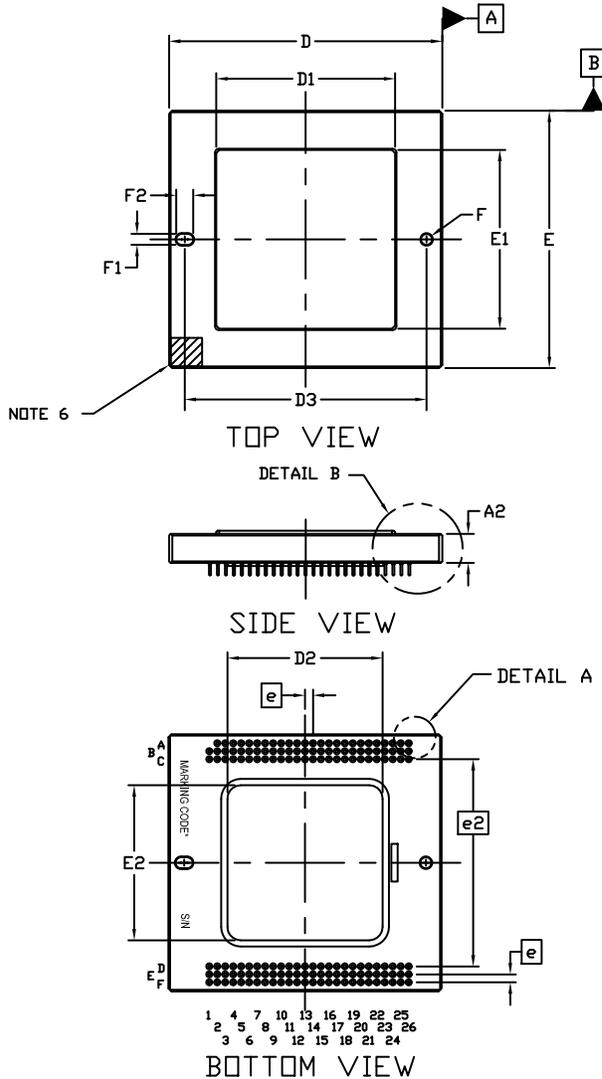
## PACKAGE DIMENSIONS

ON Semiconductor®



### CPGA155 43.5x41 CASE 107FG ISSUE O

DATE 24 JAN 2017



**NOTES:**

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION A INCLUDES THE PACKAGE BODY, GLASS, AND HEATSINK.
- DIMENSIONS D AND E DO NOT INCLUDE PROTRUSIONS. SUCH PROTRUSIONS SHALL NOT EXTEND MORE THAN 0.08 ON ANY SIDE. CORNERS AND EDGES OF THE PACKAGE MAY HAVE CHAMFERS.
- THE SEATING PLANE IS DEFINED BY THE OUTER HEATSINK SURFACE.
- PIN A1 IDENTIFICATION WILL BE IN THIS AREA. ID TYPE MAY CONSIST OF NOTCHES, METALLIZED MARKINGS, OR OTHER FEATURES.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	5.62 REF		
A1	0.45	0.50	0.55
A2	4.15	4.61	5.07
A3	0.50 REF		
b	0.25	0.30	0.35
D	43.10	43.50	43.90
D1	28.42	28.50	28.58
D2	24.55	24.70	24.85
D3	38.15	38.50	38.85
E	40.59	41.00	41.41
E1	28.42	28.50	28.58
E2	24.55	24.70	24.85
e	1.27 BSC		
e2	33.02 BSC		
F	1.65	1.75	1.85
F1	1.65	1.75	1.85
F2	2.57	2.72	2.87
L	1.80	2.00	2.20

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>CPGA155 43.5X41</b>	<b>PAGE 1 OF 2</b>

